

# China 3D IC and 2.5D IC Packaging Market Research Report 2018

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### **Abstracts**

The global 3D IC and 2.5D IC Packaging market is valued at XX million USD in 2016 and is expected to reach XX million USD by the end of 2022, growing at a CAGR of XX% between 2016 and 2022.

China plays an important role in global market, with market size of xx million USD in 2016 and will be xx million USD in 2022, with a CAGR of xx%.

This report studies the 3D IC and 2.5D IC Packaging development status and future trend in China, focuses on top players in China, also splits 3D IC and 2.5D IC Packaging by type and by applications, to fully and deeply research and reveal the market general situation and future forecast.

The major players in China market include

Taiwan Semiconductor

Samsung Electronics

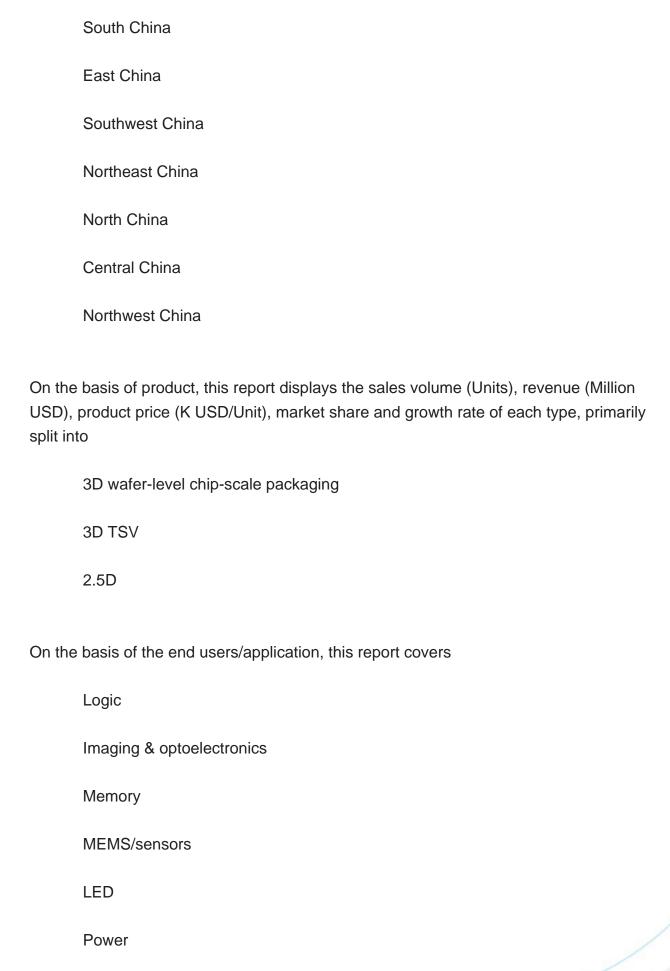
Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

Geographically, this report splits the China market into six regions,







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